Product End-of-Life Disassembly Instructions

Product Category: Networking Equipment
Marketing Name / Model [List multiple models if applicable.]
HP FlexFabric 11908-V Switch Chassis (JG608A)
HP A10508-V Switch Chassis (JC611A)
HP 10508-V TAA Switch Chassis (JG822A)

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	3
Batteries	All types including standard alkaline and lithium coin or button style batteries	0
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2#

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unscrew the screws on mounting angle 2, and then remove the left and right mounting angles 2 from the chassis.
2. Unscrew the screws on front panel 3, and then remove front panel 3 from the chassis.
3. Unscrew the screws on blank panel 4 and then remove front blank panel 4 from the chassis.
4. Unscrew the screws on front panel 5, and then remove front panel 5 from the chassis.
5. Unscrew the screws on power cable channel sets 6, and then remove power cable channel sets 6 from the chassis.
6. Remove power module 7 from the chassis.
7. Unscrew the screws on blank power module panel 8, and then remove blank power module panel 8 from the chassis.
8. Unscrew the screws on dust filter 9, and then remove the dust filter 9 from the chassis.
9. Unscrew the screws on upper wire channel sets 10, and then remove upper wire channel sets 10 from the chassis.
10. Remove the film 11 from the chassis.
11. Unscrew the screws on fan frame 12, and then remove fan frame 12 from the chassis.
12. Unscrew the screws on flue panel A 13, and then remove the flue panel A 13 from the chassis.
13. Unscrew the screws on net board panel 14, and then remove net board panel 14 from the chassis.
14. Unscrew the screws on flue panel B 15, and then remove the flue panel B 15 from the chassis.
15. Unscrew the screws on net blank panel 16, and then remove net blank panel 16 from the chassis.
16. Unscrew the screws on flue panel C 17, and then remove the flue panel C 17 from the chassis.
17. Unscrew the screws on flue panel D 18, and then remove the flue panel D 18 from the chassis.
18. Unscrew the screws on back cover 19, and then remove the back cover 19 from the chassis.
19. Remove shielding finger 20 from the chassis.
20. Unscrew the screws on left and right guide rail 21, and then remove the left and right guide rail 21 from the chassis.
21. Unscrew the screws on PCB 22, and then remove PCB 22.
22. Unscrew the screws on strengthen plate 23, and then remove the strengthen plate 23.
23. Unscrew the screws on back right rail 24, and then remove the back right rail 24 from the chassis.
24. Unscrew the screws on PCB 25, and then remove PCB 25.
25. Remove the film 26 from the chassis.
26. Unscrew the screws on back left rail 27, and then remove the back left rail 27 from the chassis.
27. Unscrew the screws on part 3-2, and then remove part 3-2 from front panel 3-1.
28. Unscrew the screws on pcb 3-3, and then remove pcb 3-3 from front panel 3-1.
29. Remove shielding finger 3-4 from front panel 3-1.
30. Remove film 3-5 from front panel 3-1.
31. Unscrew the screws on part 4-2, and then remove part 4-2 from front blank panel 4-1.
32. Remove shielding finger 4-3 from front blank panel 4-1.
33. Remove film 4-4 from front blank panel 4-1.
34. Remove shielding finger 5-2 from panel 5-1.
35. Remove film 5-3 from panel 5-1.
36. Unscrew the screws on sheet metal 5-4,and then remove sheet metal 5-4.
37. Unscrew the screws on PCB 5-5,and then remove PCB 5-5.
38. Unscrew the screws on PCB 5-6,and then remove PCB 5-6.
39. Unscrew the screws on power cable channel sets 6, and then remove the blocks 6-2 from wire road board 6-1
40. Unscrew the screws on power cable channel sets 6, and then remove the blocks 10-2 from wire road board 10-1.
41. Remove the film 10-3 from the wire road board 10-1.
42. Unscrew the screws on power cable channel sets 6, and then remove the cable bars 10-4 from wire road board 10-1.

43. Unscrew the screws on fan frame 12, and then remove the protect nets 12-1 from fan frame 12.
44. Unscrew the screws on fan frame 12, and then remove the top cover 12-2 from fan frame 12.
45. Remove the fans 12-3.
46. Remove the film 12-5 from the fan frame 12-4.
47. Unscrew the screws on fan frame 12-4,and then remove the handle from the fan frame 10-4.
48. Unscrew the screws on fan frame 12-4, and then remove PCB 12-7.
49. Remove the EMIS 10-8 from the fan frame 12-4.
50. Unscrew the screws on part 13-2, and then remove part 13-2 from flue panel A 13-1.
51. Unscrew the screws on pcb 14-2, and then remove pcb 14-2 from front panel 14-1.
52. Remove shielding finger 14-3 from front panel 14-1.
53. Remove film 14-4 from front panel 14-1.
54. Unscrew the screws on part 15-3, and then remove part 15-3 from flue panel B 15-1.
55. Remove shielding finger 15-2 from flue panel B 15-1.
56. Unscrew the screws on part 16-2, and then remove part1 16-2 from net blank panel16-1.
57. Remove shielding finger 16-3 from net blank panel 16-1.
58. Remove film 16-4 from net blank panel 16-1.
59. Unscrew the screws on part 17-2, and then remove part 17-2 from flue panel C 17-1.
60. Remove shielding finger 17-3 from flue panel C 17-1.
61. Unscrew the screws on part 18-2, and then remove part 18-2 from flue panel C 18-1.
62. Remove shielding finger 18-3 from flue panel D 18-1.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

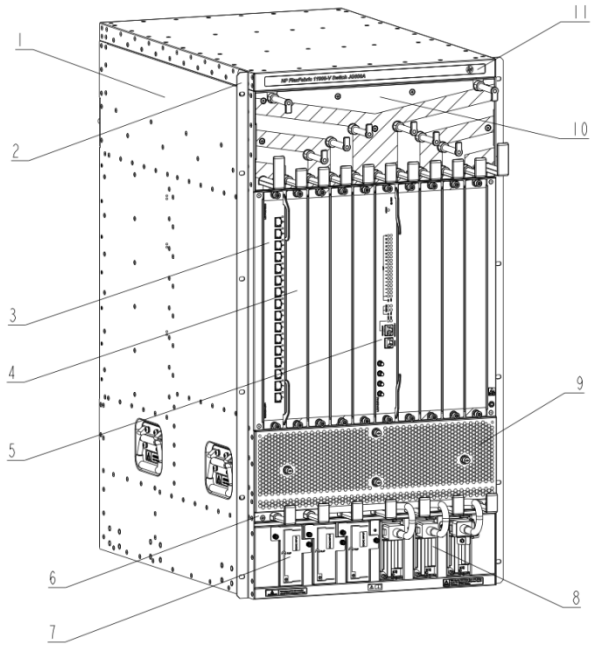

Figure 1 Treatments to the product（front view）

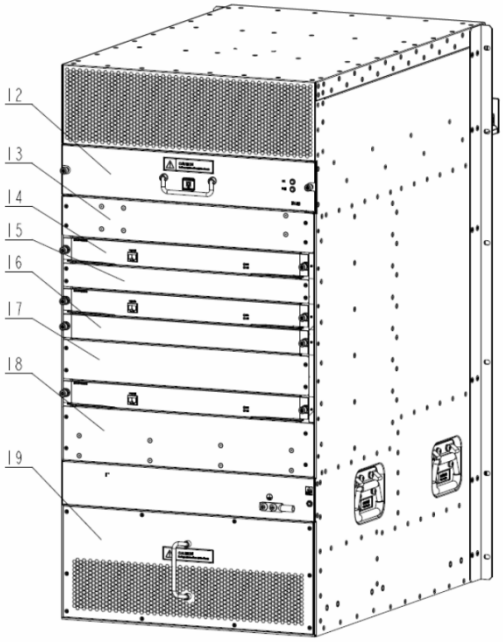

Figure 2 Treatments to the product (rear view)

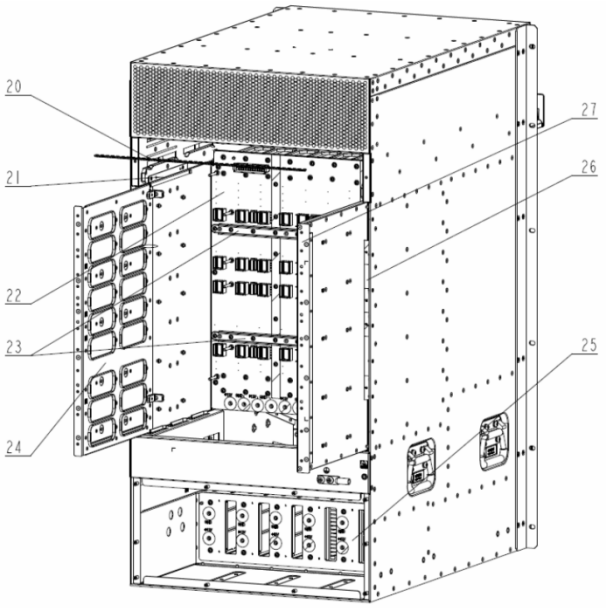

Figure 3 Treatments to the product (rear view)

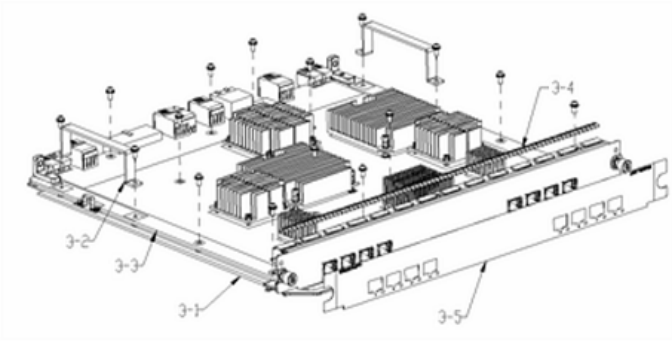

Figure 4 Treatments to front panel 3.

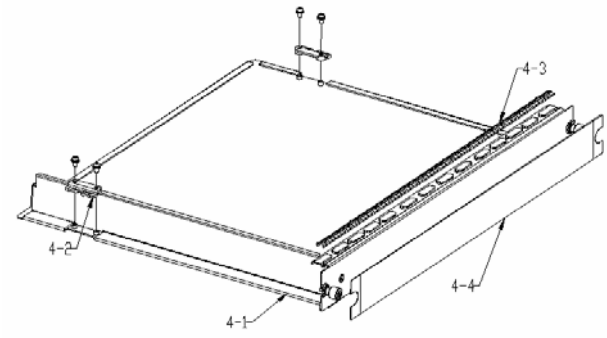

Figure 5 Treatments to front blank panel 4

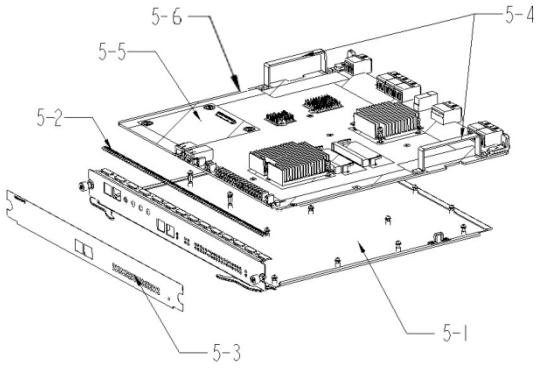

Figure 6 Treatments to front panel 5

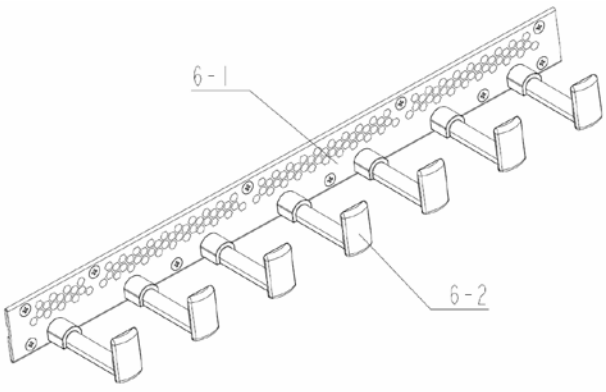

Figure 7 Treatments to upper wire channel sets 6

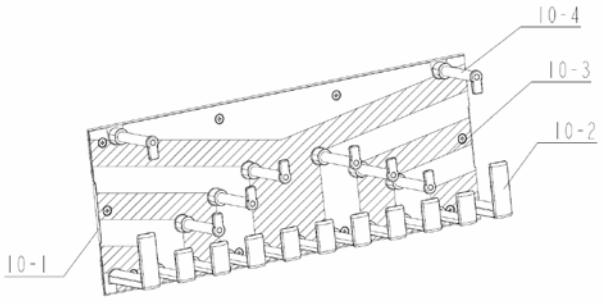

Figure 8 Treatments to upper wire channel sets 10

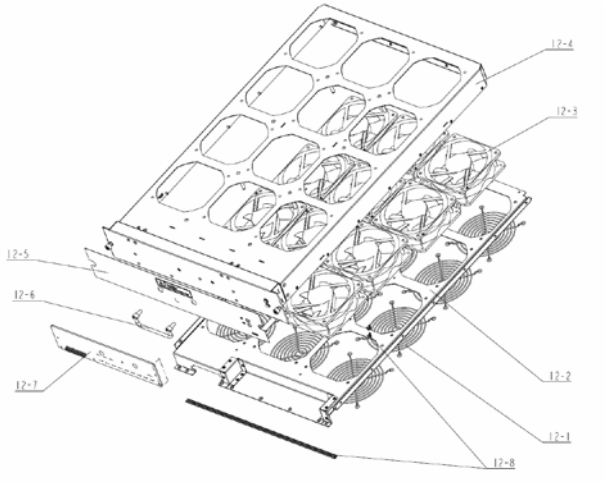

Figure 9 Treatments to fan frame 12

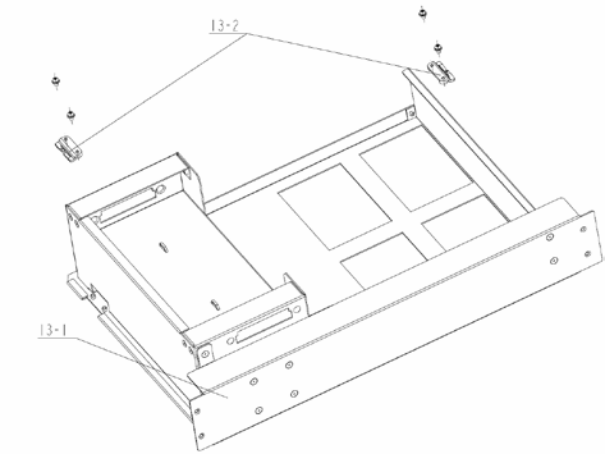

Figure 10 Treatments to flue panel A 13

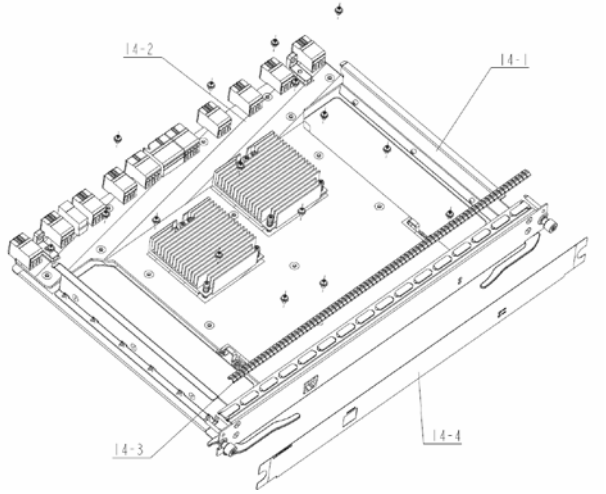

Figure 11 Treatments to net board panel 14

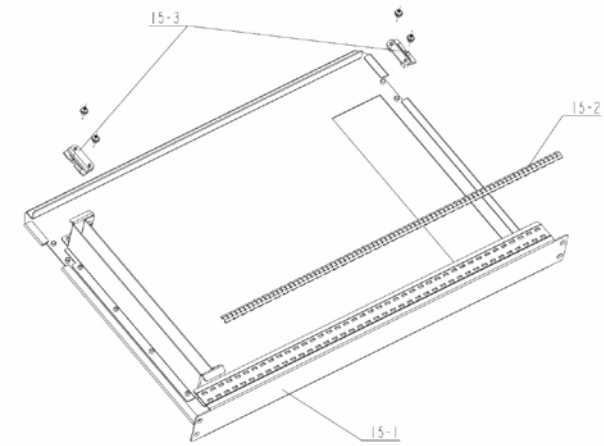

Figure 12 Treatments to flue panel B 15

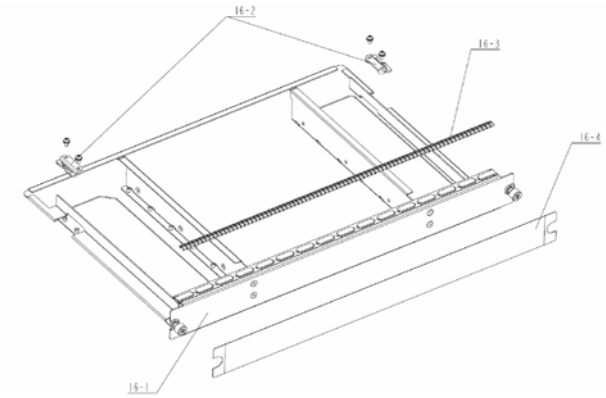

Figure 13 Treatments to net blank panel 16

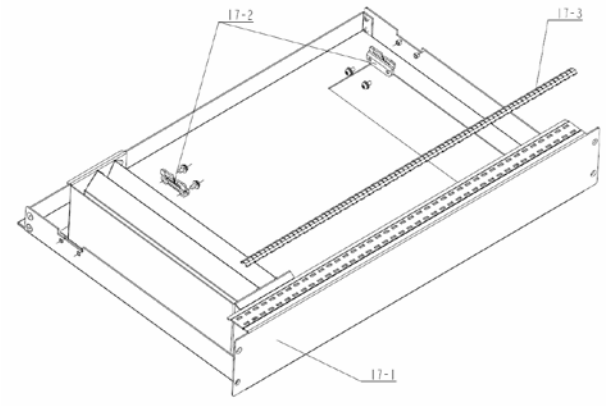

Figure 14 Treatments to flue panel C 17

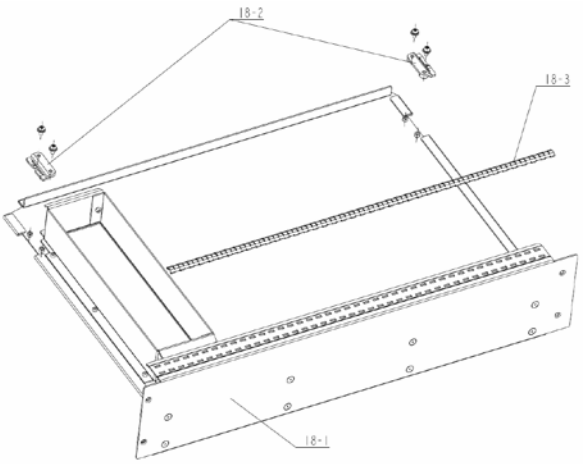

Figure 15 Treatments to flue panel D 18

3.3 Material of the facility built

Facility	Components	Material	Weight(g)	Weight percentage	Selective treatment for materials and components	Details
1		Fe	59143.254	50.33%		Fe recycling
2		Fe	825.6*2	1.4%		Fe recycling
3						
	3-1	Fe	1490	1.27%		
	3-2	Fe	25*2	0.04%		Fe recycling
	3-3	Complex PWB	1250	1.06%	The surface of PCB is greater than 10 square centimeters	
	3-4	Be-Cu	4.3	0.001%		Cu recycling
	3-5	PC	2	0.0005%	Containing brominated flame retardants	Pla recycling
4						
	4-1	Fe	1550	1.32%		Fe recycling
	4-2	PA	2	0.0005%		Pla recycling
	4-3	Be-Cu	4.3	0.001%		Cu recycling
	4-4	PC	2	0.0005%	Containing brominated flame retardants	Pla recycling
5						
	5-1	Fe	1540	51.28%		Fe recycling
	5-2	Be-Cu	4	0.13%		Cu recycling
	5-3	PC	5	0.17%	Containing brominated flame retardants	Pla recycling
	5-4	Fe	24	0.80%		Fe recycling
	5-5	Complex PWB	250	8.33%	The surface of PCB is greater than 10 square centimeters;	
	5-6	Complex PWB	1180	39.29%	The surface of PCB is greater than 10 square centimeters;	
6						
	6-1	Fe	313.7	0.26%		Fe recycling
	6-2	Al	25.12*7	0.14%		Al recycling

7			2500*3	6.36%		
8		Fe	129.2*3	0.32%		Fe recycling
9		Fe	632.1	0.53%		Fe recycling
10		PC	25	0.02%	Containing brominated flame retardants	Pla recycling
11		PC	2.24	0.001%	Containing brominated flame retardants	Pla recycling
12						
	12-1	Fe	39.6*12	0.40%		Fe recycling
	12-2	Fe	1315.8	1.12%		Fe recycling
	12-3		350*12	3.57%		
	12-4	Fe	2433.7	2.07%		Fe recycling
	12-5	PC	9.98	0.01%	Containing brominated flame retardants	Pla recycling
	12-6	Al	37	0.03%		Al recycling
	12-7	Complex PWB	100	0.09%	The surface of PCB is greater than 10 square centimeters	
	12-8	Be-Cu	4.5	0.001%		Cu recycling
13						Fe recycling
	13-1	Fe	2655.3	2.26%		Fe recycling
	13-2	PA	2	0.0005%		Pla recycling
14						
	14-1	Fe	1474.7	1.26%		Fe recycling
	14-2	Complex PWB	1019	0.87%	The surface of PCB is greater than 10 square centimeters	
	14-3	Be-Cu	4.3	0.001%		Cu recycling
	14-4	PC	2	0.001%	Containing brominated flame retardants	Pla recycling
15						
	15-1	Fe	1460.5	1.24%		Fe recycling
	15-2	PA	2	0.001%		Pla recycling
	15-3	Be-Cu	4.3	0.001%		Cu recycling
16						
	16-1	Fe	1409.4	1.20%		Fe recycling
	16-2	PA	2	0.001%		Pla recycling
	16-3	Be-Cu	4.3	0.001%		Cu recycling
	16-4	PC	2	0.001%		Pla recycling
17						
	17-1	Fe	1873.7			Fe recycling
	17-2	PA	2	0.001%		Pla recycling
	17-3	Be-Cu	4.3	0.001%		Cu recycling
18						
	18-1	Fe	2011.8	1.71%		Fe recycling
	18-2	PA	2	0.001%		Pla recycling
	18-3	Be-Cu	4.3*2	0.002%		Cu recycling
19		Fe	774	0.66%		Fe recycling
20		Be-Cu	4.3	0.001%		Cu recycling
21		Fe	30.5*2	0.05%		Fe recycling

22		Complex PWB	2950	2.54%	The surface of PCB is greater than 10 square centimeters	
23		Fe	138.7*2	0.24%		Fe recycling
24		Fe	3136.3	2.67%		Fe recycling
25		Complex PWB	650	0.55%	The surface of PCB is greater than 10 square centimeters	
26		PC	0.65			Pla recycling
27		Fe	3136.3	2.67%		Fe recycling
Cables						
	0404A0DF 0404AODE 0404AODH 0404A085	Pla,Cu	710	0.60%	Containing brominated flame retardants	Pla&Cu recycling

4. Revised record

Date	Version	Author	Modify content
2013.02.19	V0	Feng Junnan	Initial version
2013.10.14	V1	Chen Longjun	Add the module JC611A and JG822A relation